

1. General description

Pressure contact thyristor in industrial standard 70mm package for use in applications requiring high blocking voltage capability, high inrush current capability and high thermal cycling performance.

2. Features and benefits

- High blocking voltage capability
- High surge current capability
- High thermal cycling performance
- Pressure contact module with high reliability
- Easy mounting

3. Applications

- Heat and Temperature Control
- Power Converter
- Industrial Motor Drive & Soft Starter
- Lighting Control
- UPS

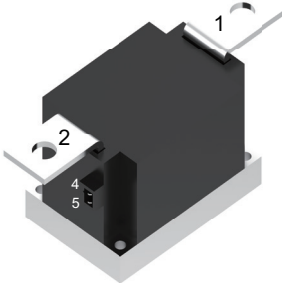
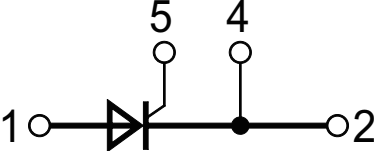
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V _{DRM}	repetitive peak forward voltage			1600			V
V _{RRM}	repetitive peak reverse voltage			1600			V
I _{T(AV)}	average on-state current	half sine wave; T _c = 85 °C		800			A
I _{TSM}	non-repetitive peak on-state current	half sine wave; T _{j(init)} = 25 °C; t _p = 10 ms		35000			A
		half sine wave; T _{j(init)} = 125 °C; t _p = 10 ms		30000			A
		half sine wave; T _{j(init)} = 25 °C; t _p = 8.3 ms		38500			A
		half sine wave; T _{j(init)} = 125 °C; t _p = 8.3 ms		33000			A
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C		30	-	150	mA
V _{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C		-	-	2.5	V
V _T	on-state voltage	I _T = 2400 A; T _j = 25 °C		-	-	1.55	V

5. Pinning information

Table 2. Pinning information

Simplified outline	Graphic symbol
	

6. Ordering information

Table 3. Ordering information

Type number	Orderable part number	Packing method	Small packing quantity
WTMS800G16	WTMS800G16T	Tray	4

7. Marking

Table 4. Marking codes

Type number	Marking codes
WTMS800G16	WTMS800G16

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{DRM}	repetitive peak forward voltage			1600	V
V_{RRM}	repetitive peak reverse voltage			1600	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_c = 85\text{ °C}$		800	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_c = 85\text{ °C}$		1256	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{J(init)} = 25\text{ °C}$; $t_p = 10\text{ ms}$		35000	A
		half sine wave; $T_{J(init)} = 125\text{ °C}$; $t_p = 10\text{ ms}$		30000	A
		half sine wave; $T_{J(init)} = 25\text{ °C}$; $t_p = 8.3\text{ ms}$		38500	A
		half sine wave; $T_{J(init)} = 125\text{ °C}$; $t_p = 8.3\text{ ms}$		33000	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN; $T_{vj} = 25\text{ °C}$		6125	kA^2s
		$t_p = 10\text{ ms}$; SIN; $T_{vj} = 125\text{ °C}$		4500	kA^2s
di_T/dt	rate of rise of on-state current	$I_G = 1.5\text{ A}$; $T_J = 125\text{ °C}$		250	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current			10	A
V_{RGM}	peak reverse gate voltage			5	V
P_{GM}	peak gate power			20	W
$P_{G(AV)}$	average gate power	over any 20 ms period		0.5	W
T_{vj}	virtual junction temperature			-40 to 125	$^{\circ}\text{C}$
T_{op}	operation temperature			-40 to 125	$^{\circ}\text{C}$
T_{stg}	storage temperature			-40 to 125	$^{\circ}\text{C}$

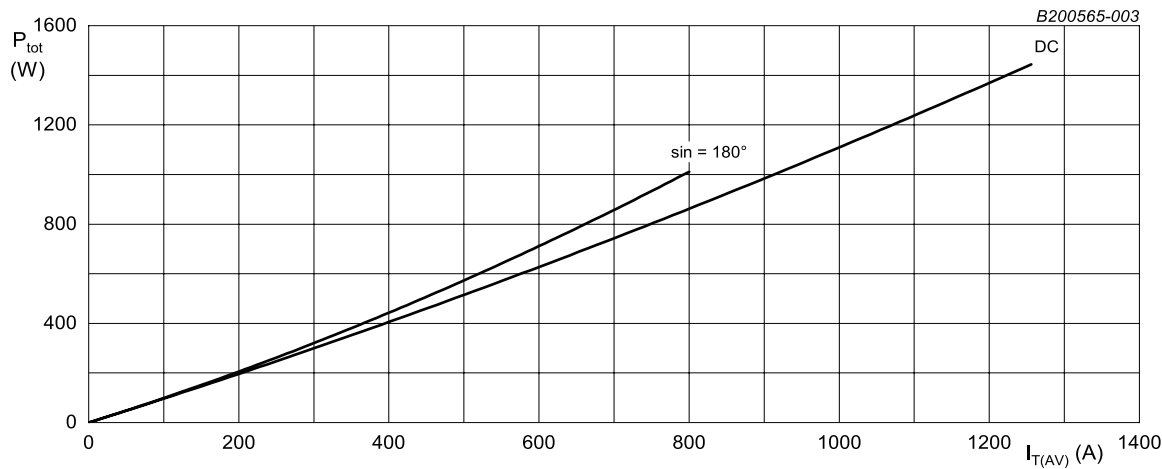
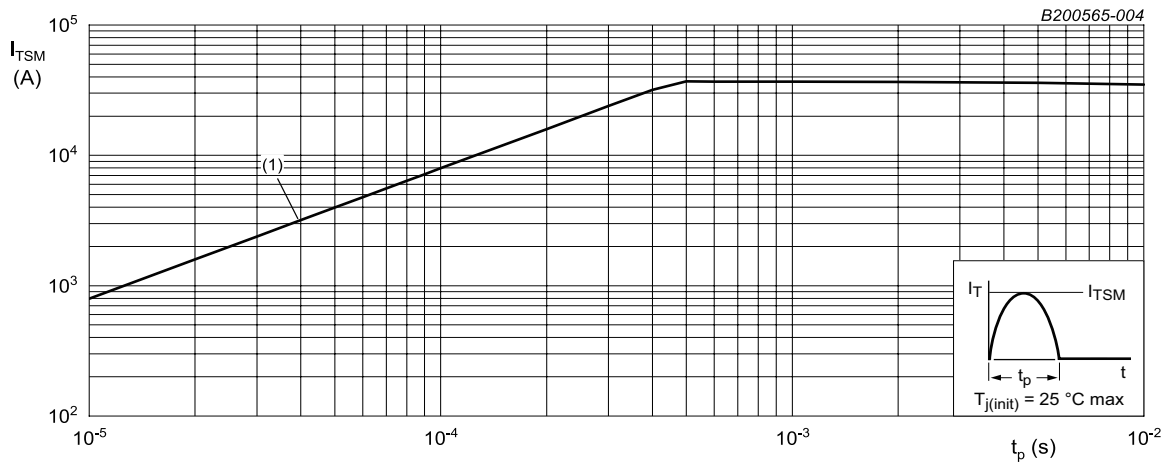


Fig. 1. Total power dissipation as a function of average on-state current; maximum values; per thyristor



$t_p \leq 10\text{ ms}$
(1) di_T/dt limit

Fig. 2. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	per thyristor	-	-	0.042	K/W
$R_{th(j-h)}$	thermal resistance from junction to heatsink	per thyristor	-	-	0.03	K/W

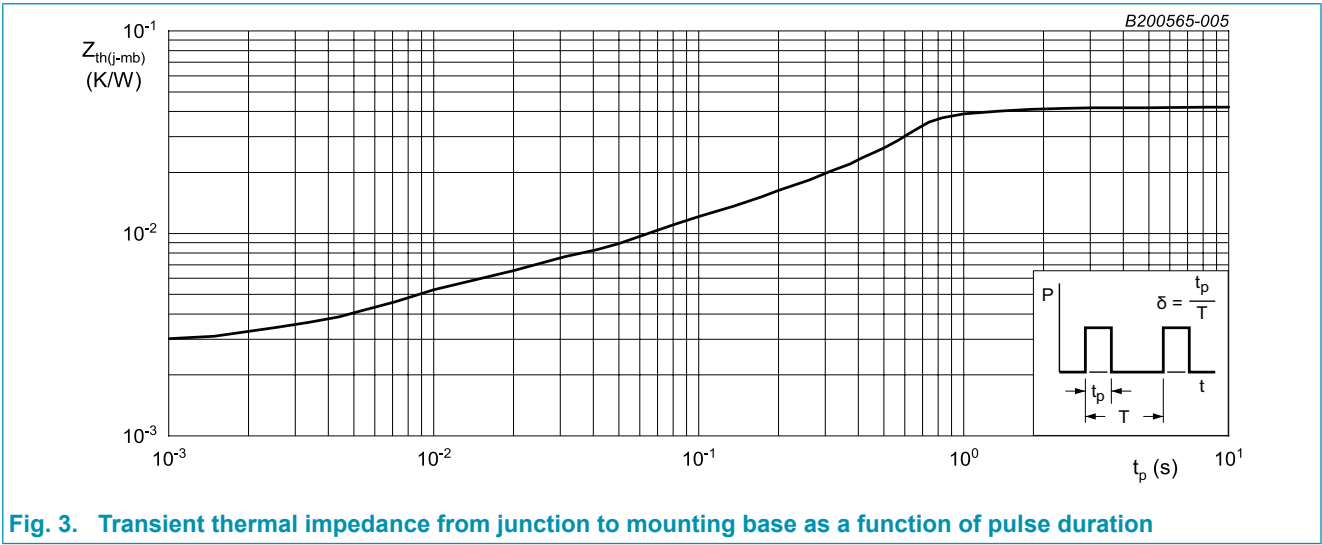


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Package characteristics

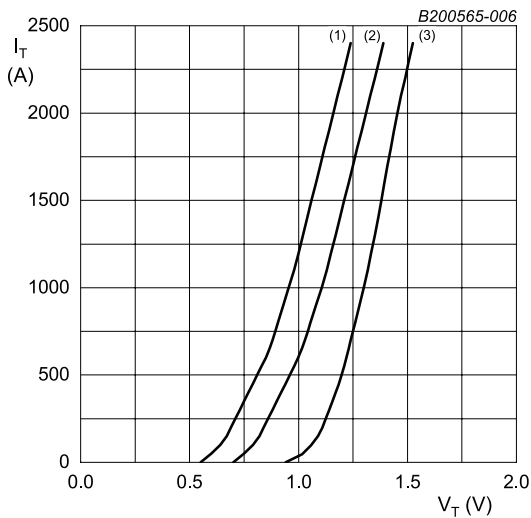
Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{isol}	isolation voltage	50/60 Hz; RMS; t = 1 minute; AC	-	-	3000	V

11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C		30	-	150	mA
V _{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C		-	-	2.5	V
I _{GD}	gate non-trigger current	T _j = 125 °C		-	-	10	mA
V _{GD}	gate non-trigger voltage	T _j = 125 °C		-	-	0.25	V
I _L	latching current	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C		-	-	500	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C		-	-	150	mA
V _T	on-state voltage	I _T = 2400 A; T _j = 25 °C		-	-	1.55	V
V _{TO}	threshold voltage	T _j = 125 °C		-	-	0.95	V
r _T	slope resistance	T _j = 125 °C		-	-	0.16	mΩ
I _D	off-state current	V _D = 1600 V; T _j = 25 °C		-	-	5	mA
		V _D = 1600 V; T _j = 125 °C		-	-	70	mA
I _R	reverse current	V _R = 1600 V; T _j = 25 °C		-	-	5	mA
		V _R = 1600 V; T _j = 125 °C		-	-	70	mA
Dynamic characteristics							
dV _D /dt	rate of rise of off-state voltage	V _{DM} = 1072 V; T _j = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit		1500	-	-	V/μs
t _{gt}	gate-controlled turn-on time	V _D = 800 V; I _G = 300 mA; (dI _G /dt) _M = 1 A/μs; T _j = 25 °C		-	5	-	μs
t _q	commutated turn-off time	I _{TM} = 2 A; t _p = 50 μs; dV _D /dt = 5 V/μs; dI/dt = 30 A/μs; T _j = 25 °C		-	150	-	μs



$V_{TO} = 0.950\text{ V}$; $r_T = 0.00016\ \Omega$
(1) $T_J = 125\text{ }^\circ\text{C}$; typical values
(2) $T_J = 125\text{ }^\circ\text{C}$; maximum values
(3) $T_J = 25\text{ }^\circ\text{C}$; maximum values

Fig. 4. On-state current as a function of on-state voltage

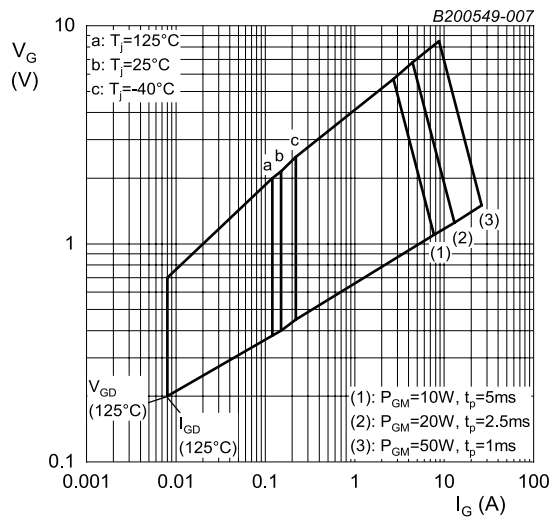
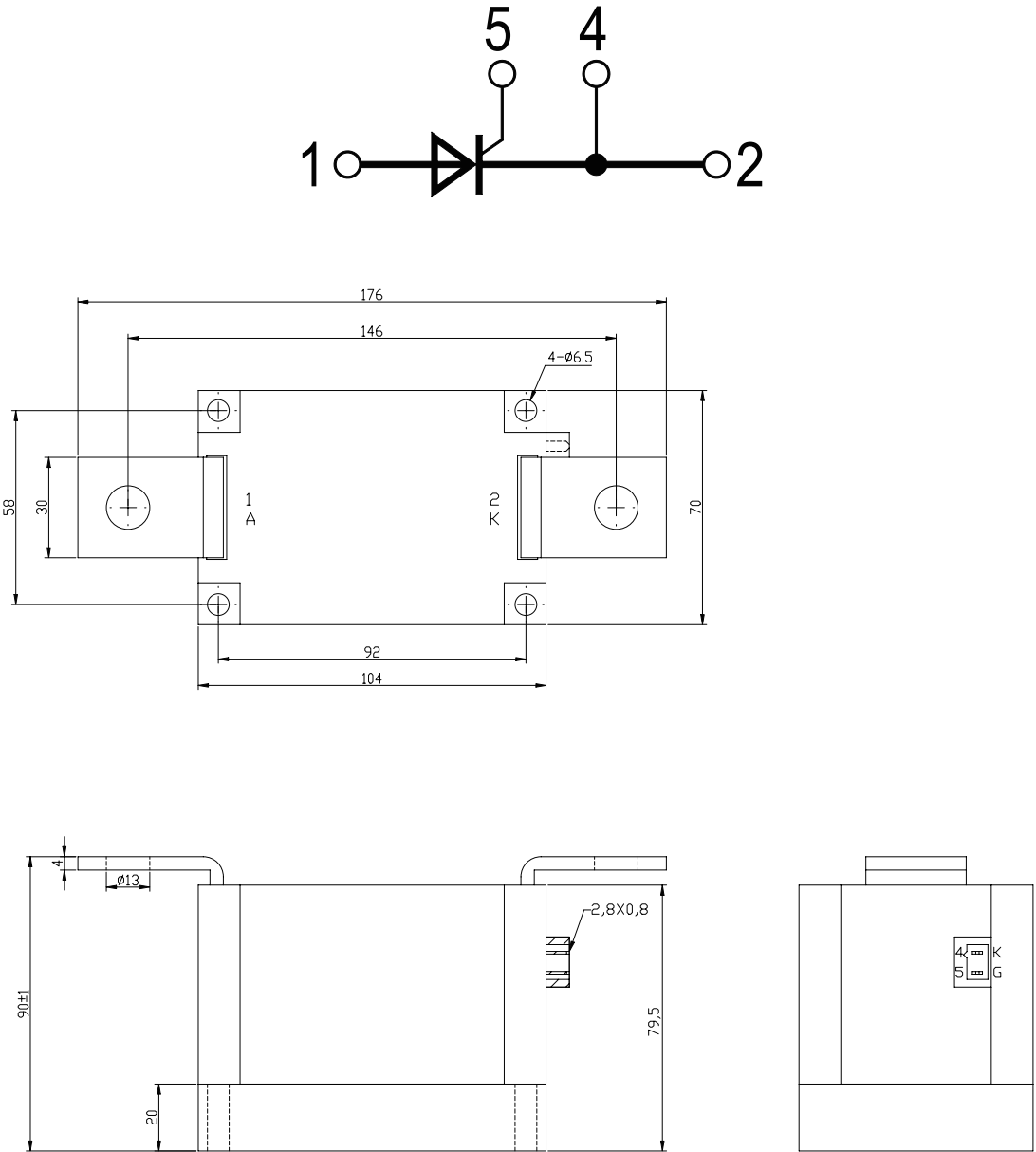


Fig. 5. Gate voltage as a function of gate current

12. Package outline

Package Outline

Dimensions in mm



General tolerance ±0.5mm

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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